

IIT Kharagpur Online Certification Programme

on

Introduction to Devices and Systems Packaging



- Introduction to Semiconductors and Packaging: Prof. Tummala, Georgia Tech
- Introduction to Devices: Prof. Abhisek Dixit, IITD
- Fundamentals of Electrical Design: Prof. M. Swaminathan, Penn State
- Fundamentals of Thermal Technologies: Prof. A. Bhattacharya, IITKGP
- Fundamentals of Thermo-mechanical Reliability: Prof. Andrew Tay, NUS
- Fundamentals of Package Materials: Dr. Ravi Bhatkal, MacDermid Alpha India
- Fundamentals of Substrates: Dr. Sundaram, System Scaling
- Fundamentals of Passive Components and Their Integration: Prof. R. Pulugurtha, FIU
- Fundamentals of Chip-to-Package Interconnect. & Assembly: Prof. Vanessa Smet, Georgia Tech
- Fundamentals of Embedded & Fan Out packaging: Dr. Beth Keser, Intel
- Fundamentals of 3D Packaging With and without TSV: Dr. Subbu Iyer, UCLA
- Fundamentals of RF and Millimeter-wave Packaging: Prof. M. Tentzeires, Georgia Tech
- Fundamentals of Opto-electronics packaging: Dr. Ajey Jacobs, USC
- Fundamentals of MEMS and Sensors packaging: Prof. Farrokh Ayazi, Georgia Tech
- Fundamentals of Encapsulation, Molding, & Sealing: Prof. Jack Moon, Georgia Tech
- Fundamentals of Printed Wiring Boards: Dr. Sundar Kamath, Sanmina
- Fundamentals of Board Assembly: Prof. Nilesh Badwe, IITK
- Automotive electronics: Prof. Kaushik Basu, IISc
- Computing Systems: Dr. Ravi Mahajan, Intel
- Flexible Electronics: Prof. S.K. Iyer, IITK
- Memory Packaging: Dr. Gokul Kumar, Micron

Start Date: Aug 19, 2023

- 40 hours of instruction taught by global experts

Course Fees

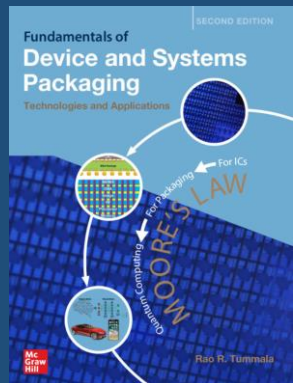
Industry Professional: INR 60,000 + GST

Academic faculty: INR 30,000 + GST

Students: INR 10,000 + GST

Text book:

Rao R. Tummala, 2020, *Fundamentals of Device and Systems Packaging: Technologies and Applications*, McGraw Hill, 2nd Edition, India



For more details, please contact Prof. A. Bhattacharya (anandaroop@mech.iitkgp.ac.in)